Book Report:

Structural Analysis in Microelectronics, by E. Suhir. Publisher: Van Nostrand, New York, $69.95.

REVIEWED BY P. A. ENGEL

The author prepares his audience for electronic packaging structural analysis by outlining the necessary theories of 1) Elasticity and 2) Structural analysis. I found it a very readable and learned summary of these subjects, albeit presented rather succinctly and economically, without many examples.

The internal organization of chapters is good, and I found no technical errors. Individual subjects, for example Viscoelasticity, were treated rather tersely because the avowed purpose was to furnish a supporting text for further use; thus the author had to practice his judgment how much material could be omitted without skimping on substance. Each sub-chapter has its own vast literature, but good sets of references were given pointing to the most substantive pieces of literature.

The chapters aim at reaching a rather well-educated reader, (senior undergraduate or graduate student, or researcher) for whom reading of the book would be an excellent recapitulation and source of material.

Each section is introduced well—clearly the author writes with familiarity and a deep identification with the subject matter. These introductory statements give a good start for the reading to follow. There is adequate connection between the various parts of the book; both concepts, notation, and style tie it successfully together.

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